



## Material Content Data Sheet



<b>Sales Product Name</b>		SPS02N60C3		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA000354126						
<b>Package</b>		PG-TO251-3-311		<b>Weight*</b>		330.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.473	0.45	0.45	4453	4453
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		141	
	non noble metal	iron	7439-89-6	0.156	0.05		470	
	non noble metal	copper	7440-50-8	155.372	46.98	47.04	469774	470385
	non noble metal	aluminium	7429-90-5	0.510	0.15	0.15	1543	1543
wire	inorganic material	antimonytrioxide	1309-64-4	2.047	0.62		6188	
encapsulation	plastics	brominated resin	-	2.193	0.66		6630	
	organic material	carbon black	1333-86-4	2.339	0.71		7072	
	plastics	epoxy resin	-	19.735	5.97		59668	
	inorganic material	silicondioxide	60676-86-0	119.870	36.24	44.20	362430	441988
leadfinish	non noble metal	tin	7440-31-5	3.002	0.91	0.91	9075	9075
plating	inorganic material	phosphorus	7723-14-0	0.004	0.00		11	
	non noble metal	nickel	7440-02-0	1.555	0.47	0.47	4700	4711
solder	non noble metal	tin	7440-31-5	0.036	0.01		109	
	noble metal	silver	7440-22-4	0.045	0.01		136	
	non noble metal	lead	7439-92-1	1.714	0.52	0.54	5183	5428
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		19	
	non noble metal	iron	7439-89-6	0.021	0.01		62	
	non noble metal	copper	7440-50-8	20.617	6.23	6.24	62336	62417
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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